

Docket No. JCLA6230

101552314

Form 1595 RECORDATION FORM COVER SHEET U.S. Department of Commerce	
PATENTS ONLY	Patent and Trademark Office O 1 1 1 6 1 6
To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.	
1. Name of conveying party(ies):	2. Name/address of receiving Party(ies):
Chi-Ming Huang, Shuang-Neng Peng	Taiwan Semiconductor Manufacturing Co.,
3. Nature of conveyance: ⊠ Assignment ☐ Merger ☐ Security Agreement ☐ Other	Ltd. 121, Park Ave. III, Science-Based Industrial
☐ Change of Name ☐ Reassignmen	Park Hsin-Chu 300, Taiwan, R.O.C.
4. Date(s) of execution: Sep. 7, 2000.	Add'1 names of receiving parties Attached? ☐ Yes ☒ No
5. Application number(s) or patent number(s):	
If this documents is being filed together with a new application, the execution date of the application is <u>Sep 7, 2000</u> .	
A. Patent Application No. (s)	B. Patent No. (s)
Additional numbers attached	
6. Name and address of party to whom Correspondence concerning document	7. Total No. of applications and patents involved:
should be mailed:	ONE(1) 8. Total fee (37 CFR §3.41): \$40.00
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IRVINE, CALIFORNIA 926.8-304: (949) 251-C111	Charge to Acct. No.
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10. Statement and Signature:	
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.	
Jiawei Huang	tung ufsilan
Name of Person Signing Signature	Date

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PATENT REEL: 011330 FRAME: 0291

ASSIGNMENT

WHEREAS.

1. Chi-Ming Huang

2. Shuang-Neng Peng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CONDITIONER SET FOR CHEMICAL-MECHANICAL POLISHING STATION

[] Filed: Serial No

[x] Executed concurrently with the execution of this instrument

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd.

of 121, Park Ave. III, Science-Based Industrial Park Hsin-Chu 300, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW. THEREFORE, TC ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assign or has/have signed his/her/their name(s) on the date(s) indicated.

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Signature:

Sole or First Joint Inventor: Chi-Ming Huang

Sherming - Along Forg Date: Second Joint Inventor (if any): Shuang-Neng Peng

RECORDED: 11/30/2000

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PATENT **REEL: 011330 FRAME: 0293**